

August 2012

FGH75T65UPD 650V, 75A Field Stop Trench IGBT

Features

- Maximum Junction Temperature: T_J = 175°C
- Positive Temperaure Co-efficient for easy parallel operating
- High current capability
- Low saturation voltage: $V_{CE(sat)} = 1.65V(Typ.) @ I_C = 75A$
- High input impedance
- Tightened Parameter Distribution
- RoHS compliant
- Short Circuit Ruggedness > 5us @25°C

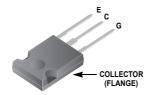


General Description

Using Novel Field Stop Trench IGBT Technology, Fairchild's new series of Field Stop Trench IGBTs offer the optimum performance for Solar Inverter , UPS and Digital Power Generator where low conduction and switching losses are essential.

Applications

· Solar Inverter, UPS, Digital Power Generator





Absolute Maximum Ratings

Symbol	Description		Ratings	Units
V _{CES}	Collector to Emitter Voltage		650	V
V _{GES}	Gate to Emitter Voltage		± 20	V
I _C	Collector Current	@ T _C = 25°C	150	А
.0	Collector Current	@ T _C = 100°C	75	A
I _{CM (1)}	Pulsed Collector Current		225	А
I _F	Diode Forward Current	@ T _C = 25°C	75	А
	Diode Forward Current	@ T _C = 100°C	50	A
I _{FM(1)}	Pulsed Diode Maximum Forward Current		225	А
P_{D}	Maximum Power Dissipation	@ T _C = 25°C	375	W
	Maximum Power Dissipation	@ T _C = 100°C	187	W
SCWT	Short Circuit Withstand Time @ T _C = 25°C		5	us
T _J	Operating Junction Temperature		-55 to +175	°C
T _{stg}	Storage Temperature Range		-55 to +175	°C
T _L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Notes:1: Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.40	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	0.86	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

Package Marking and Ordering Information

Device Marking Device		Package	Eco Status	Pacing Type	Qty per Tube
FGH75T65UPD	FGH75T65UPD	TO-247	-	-	30ea

For Fairchild's definition of "green" Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs green.html.

Electrical Characteristics of the IGBT $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	V_{GE} = 0V, I_{C} = 1mA	650	-	-	V
$\frac{\Delta BV_CES}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0V, I _C = 1mA	-	0.65	-	V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	250	μΑ
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	I _C = 75mA, V _{CE} = V _{GE}	4.0	6.0	7.5	V
. ,		I _C = 75A, V _{GE} = 15V	-	1.65	2.3	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 75A, V _{GE} = 15V, T _C = 175°C	-	2.05	-	V
Dynamic C	haracteristics					
C _{ies}	Input Capacitance		-	5665	-	pF
C _{oes}	Output Capacitance	$V_{CE} = 30V_{,} V_{GE} = 0V_{,}$ f = 1MHz	-	205	-	pF
C _{res}	Reverse Transfer Capacitance	1 - IIVINZ	-	100	-	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time		-	32	42	ns
t _r	Rise Time		-	43	56	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400V, I _C = 75A,	-	166	216	ns
t _f	Fall Time	$R_G = 3\Omega$, $V_{GE} = 15V$,	-	24	33	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C	-	2.85	3.68	mJ
E _{off}	Turn-Off Switching Loss		-	1.20	1.60	mJ
E _{ts}	Total Switching Loss		-	4.05	5.3	mJ
t _{d(on)}	Turn-On Delay Time		-	30	-	ns
t _r	Rise Time		-	57	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400V, I _C = 75A,	-	176	-	ns
t _f	Fall Time	$R_G = 3\Omega$, $V_{GE} = 15V$, Inductive Load, $T_C = 175^{\circ}C$	-	21	-	ns
E _{on}	Turn-On Switching Loss		-	4.45	-	mJ
E _{off}	Turn-Off Switching Loss		-	1.60	-	mJ
E _{ts}	Total Switching Loss		-	6.05	-	mJ
Tsc	Short Circuit Withstand Time	$V_{\rm GE}$ = 15V, $V_{\rm CC}$ \leq 400V, Rg = 10 Ω	5	-	-	us

Electrical Characteristics of the IGBT (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Units
Q_g	Total Gate Charge		-	385	578	nC
Q _{ge}	Gate to Emitter Charge	V _{CE} = 400V, I _C = 75A, V _{GE} = 15V	-	45	68	nC
Q _{ac}	Gate to Collector Charge	VGE - 13 V	-	210	315	nC

Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Units
V _{FM}	Diode Forward Voltage	I _F = 50A	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	2.1	2.6	V
FIVI	Blode i Si Ward Voltage	1F - 30A	$T_{\rm C} = 175^{\rm o}{\rm C}$	-	1.7	-]
E _{rec}	Reverse Recovery Energy		$T_{\rm C} = 175^{\rm o}{\rm C}$	-	40	-	uJ
t	Diode Reverse Recovery Time	I _F =50A, dI _F /dt = 200A/μs	T _C = 25°C	-	65	85	ns
'rr	2.000 1.010.00 1.00010.9 1	ης -30/A, αις/αι - 200/A/μ3	$T_{\rm C} = 175^{\rm o}{\rm C}$	-	127	-	
Q _{rr}	Diode Reverse Recovery Charge		T _C = 25°C	-	120	170	nC
~II	2.535 No.55.55 No.55 No.		$T_{\rm C} = 175^{\rm o}{\rm C}$	-	550	1	

Figure 1. Typical Output Characteristics

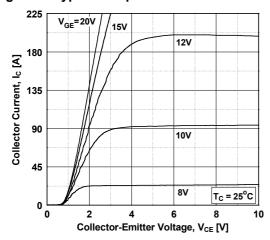


Figure 3. Typical Saturation Voltage Characteristics

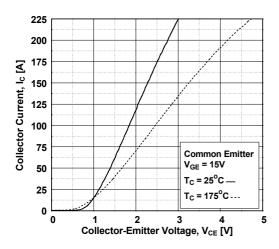


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

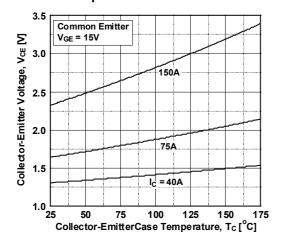


Figure 2. Typical Output Characteristics

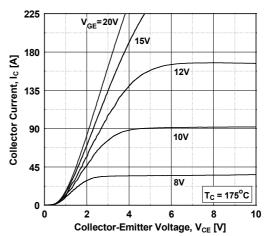


Figure 4. Transfer Characteristics

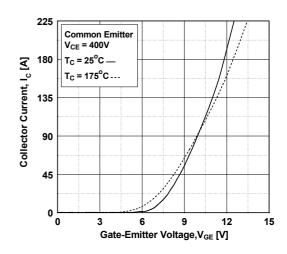


Figure 6. Saturation Voltage vs. V_{GE}

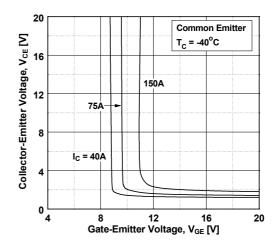


Figure 7. Saturation Voltage vs. V_{GE}

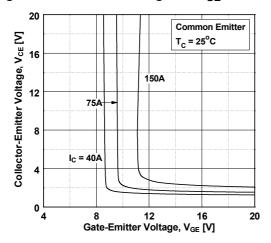


Figure 9. Capacitance Characteristics

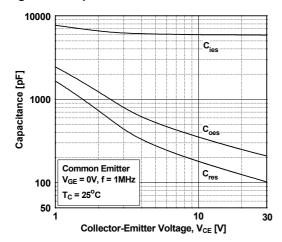


Figure 11. SOA Characteristics

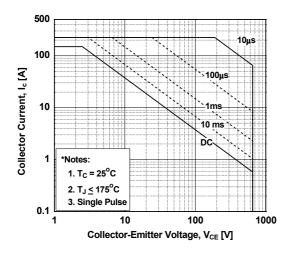


Figure 8. Saturation Voltage vs. V_{GE}

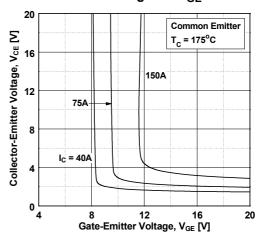


Figure 10. Gate charge Characteristics

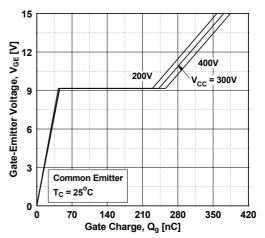


Figure 12. Turn-on Characteristics vs.

Gate Resistance

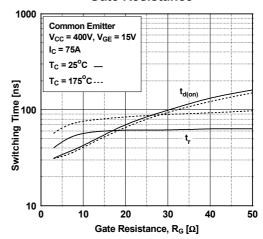


Figure 13. Turn-off Characteristics vs.
Gate Resistance

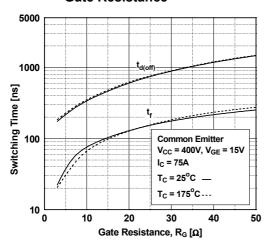


Figure 15. Turn-off Characteristics vs. Collector Current

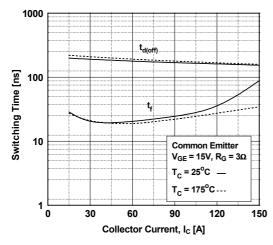


Figure 17. Switching Loss vs. Collector Current

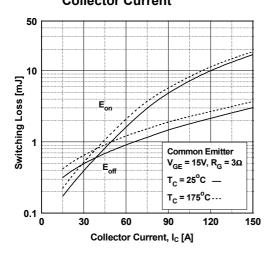


Figure 14. Turn-on Characteristics vs.
Collector Current

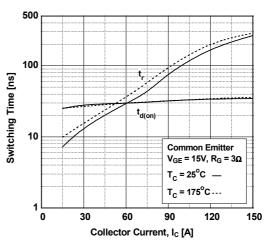


Figure 16. Switching Loss vs.

Gate Resistance

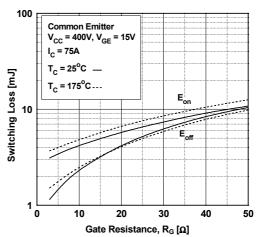


Figure 18. Turn off Switching SOA Characteristics

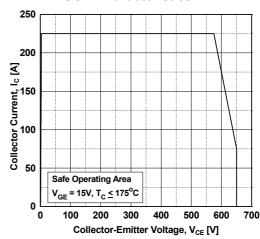


Figure 19. Current Derating

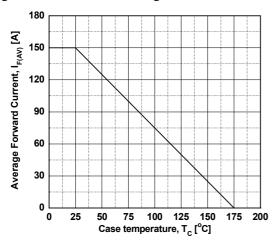


Figure 21. Forward Characteristics

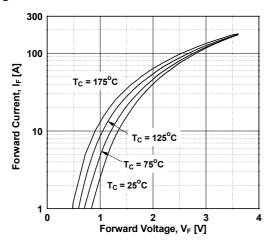


Figure 23. Stored Charge

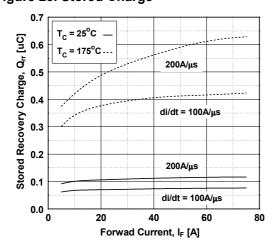


Figure 20. Load Current Vs. Frequence

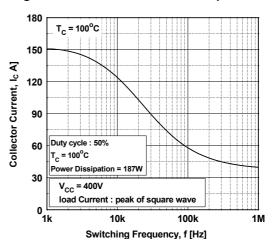


Figure 22. Reverse Recovery Current

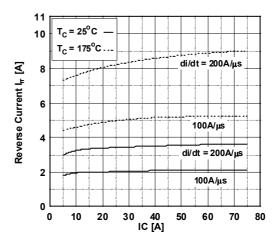


Figure 24. Reverse Recovery Time

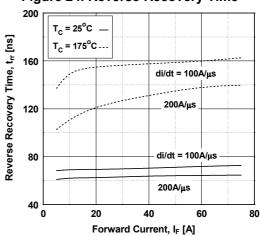


Figure 25. Transient Thermal Impedance of IGBT

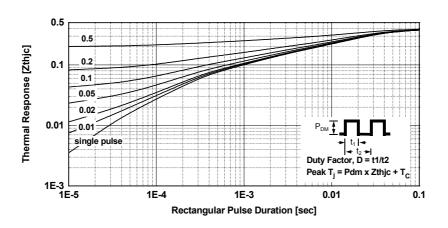
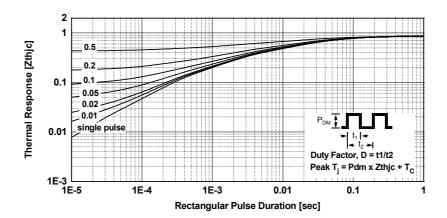
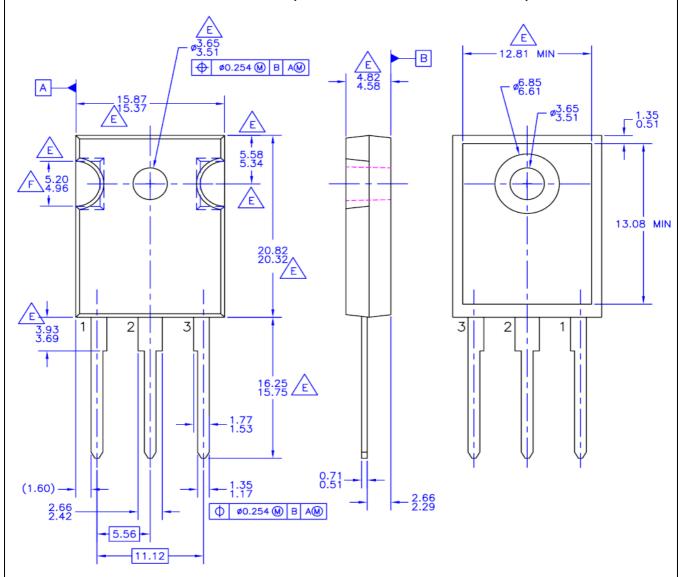


Figure 26.Transient Thermal Impedance of Diode



Mechanical Dimensions

TO - 247AB (FKS PKG CODE 001)



NOTES: UNLESS OTHERWISE SPECIFIED

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- C. ALL DIMENSIONS ARE IN MILLIMETERS.
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G. DRAWING FILENAME: MKT-TO247A03 REV02





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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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